



# BES2710IBP

Brief Datasheet

---

## Ultra-low Power Bluetooth Wearable Platform

---

### CONTACT US:

**Company:** Bestechnic (Shanghai) Co., Ltd. (“BES”)

**Address:** 2F, Building B, Lane 2889 Jinke Road, Pudong, Shanghai (201203)

**Phone:** (86)21 6877 1788

For product inquiries and more information, please visit [www.bestechnic.com](http://www.bestechnic.com).

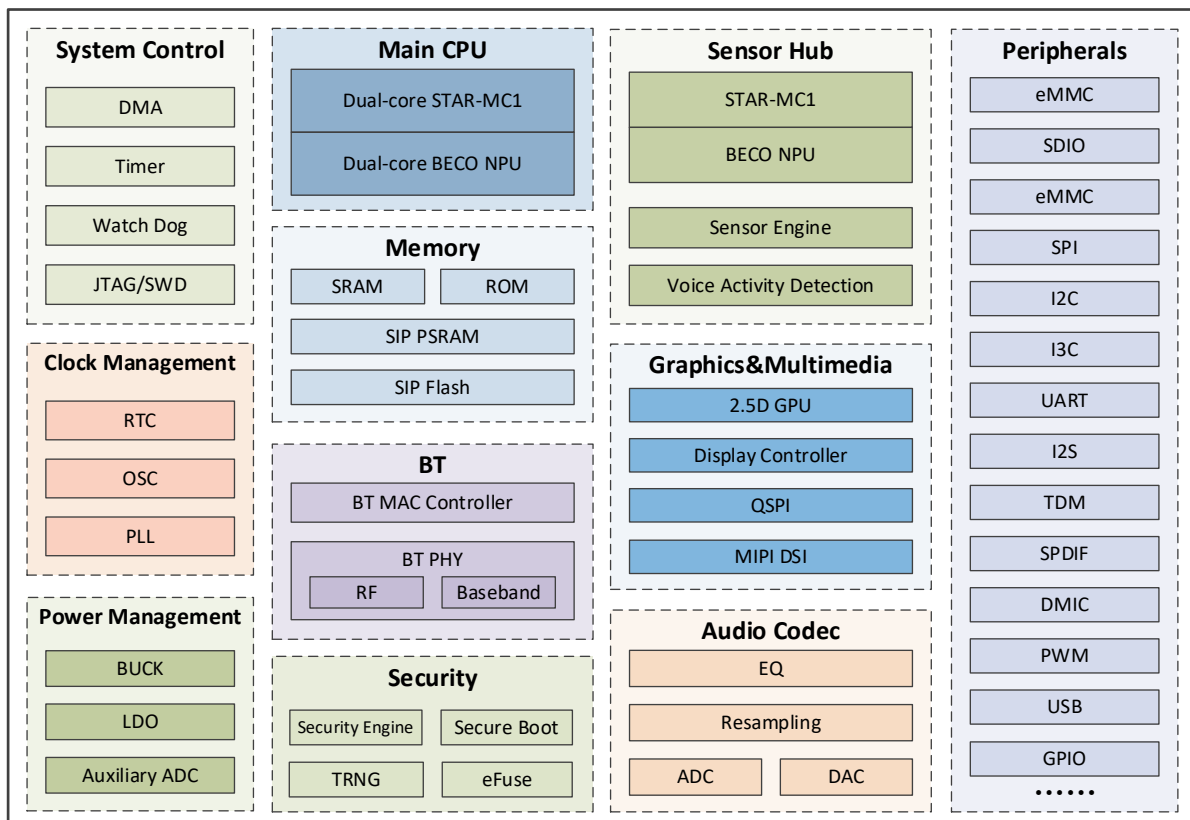
### DISCLAIMER:

*No part of this document may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, for any purpose, without the express written permission of BES. BES retains the right to make changes to this document at any time, without notice. BES makes no warranty of any kind, expressed or implied, with regard to any information contained in this document, including, but not limited to, the implied warranties of merchant ability or fitness for any particular purpose. Further, BES does not warrant the accuracy or completeness of the information, text, graphics, or other items contained within this document.*

## 1 General Description

The BES2710IBP is an ultra-low power, high performance Bluetooth wearable SoC. The platform incorporates a high performance CPU subsystem comprising a dual-core STAR-MC1 processor with a dual-core BECO NPU, a BES proprietary coprocessor for advance signal processing and NN workloads, as well as a sensor hub subsystem comprising a STAR-MC1 with a BECO NPU. This combination minimizes external components, reduces BOM costs and offers a cost-effective Bluetooth wearable solution.

The platform incorporates a dual-mode Bluetooth 5.4 subsystem, a codec subsystem and a graphics subsystem that includes a 2.5D GPU for advanced graphics features, an LCD controller with up to 3-layer alpha blending, and a 1-lane DSI with up to 500x500x24bit 60fps resolution.



System Block Diagram

### 1.1 Applications

- Bluetooth watches and wristbands
- Other wearable devices

## 1.2 Features & Specifications\*

CPU Subsystem	Dual-core STAR-MC1
Sensor Hub Subsystem	STAR-MC1
	Sensor engine
Memory and Storage	Shared 2.2 MB SRAM
	Flash and PSRAM in package
	boot ROM
Bluetooth Subsystem	Dual-mode BT 5.4 with LE audio
Graphics & Multimedia	2.5D Vector GPU
Audio & Voice Features	1x DAC
	2x ADCs
Peripheral Interfaces	eMMC/SDIO/GPADC/SPI/I2C/I3C/UART/I2S/TDM/SPDIF/DMIC/PWM/USB/GPIO.....
Package	219-pin BGA

\* The content in the table is subject to change without notice.